



Material Content Data Sheet



Sales Product Name	TLE7273-2G V33			Issued	1. August 2018			
MA#	MA000970142							
Package	PG-DSO-14-30			Weight*	143.09 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.362	1.65	1.65	16506	16506
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		422	
	non noble metal	iron	7439-89-6	1.207	0.84		8435	
wire	non noble metal	copper	7440-50-8	49.007	34.25	35.14	342491	351453
	noble metal	gold	7440-57-5	0.302	0.21	0.21	2113	2113
	encapsulation	organic material	carbon black	1333-86-4	0.173	0.12		1211
encapsulation	plastics	epoxy resin	-	7.969	5.57		55693	
	inorganic material	silicondioxide	60676-86-0	78.479	54.85	60.54	548459	605363
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8569	8569
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7197	7197
glue	plastics	acrylic resin	-	0.277	0.19		1936	
	noble metal	silver	7440-22-4	0.982	0.69	0.88	6863	8799
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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